

ABSTRACT OF THE DISCLOSURE

A multiple chips image sensor module includes a first substrate ; a photosensitive chip is arranged at the upper surface of the substrate ; a lens holder is mounted on the upper surface of the first substrate to encapsulate the photosensitive chip ; a lens barrel is arranged within the lens holder and is formed with a chamber and an opening communicating the chamber ; an aspheric and transparent layer placed within the chamber ; a second substrate is mounted on the first substrate and is electrically connected the first substrate ; and a chip located on the second surface of the second substrate.